ASSEMBLY TAPE OF INTEGRATED CIRCUIT DEVICE

Patent number: JP1205544
Publication date: 1989-08-17
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Classification:
- international: H01L21/60
- european:
Application number: JP19880030278 19880212
Priority number(s):

Abstract of **JP1205544**

PURPOSE:To eliminate the contact of a lead wire and a defect due to a short circuit and to change a position of a bonding part by forming an insulating film on the surface of a conductor foil sheet excluding a pad part and a part to be bonded to an external lead.
CONSTITUTION:A copper foil sheet 2 is formed on the surface of a polyimide film 1; a punched hole is made in the film 1; a lead wire is projected inside the punched hole by the copper foil sheet 2. A polyimide film 3 is coated and formed on the main surface of the copper foil sheet 2 excluding a part where a bump 4 of an IC chip 5 is to be bonded. By this setup, the contact of a lead wire and a defect due to a short circuit are eliminated; a position of a bonding part can be changed.